

LTM8052 81LD -LGA 15mm X 11.25mm X 2.82mm-SOLDER DA (TABLE OF MATERIAL DECLARATION)

The LTM8052 is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.1904	Barium Compounds	7727-43-7	0.00518	2.72
				Bismaleimide/Triazine/Resin/Filler Substance(Silica Crystalline)	105391-33-1,1156-51-0/9003-36-5/21645-51-2	0.03485	18.31
				Copper Metal	7440-50-8	0.12590	66.14
				Copper Compounds	1328-53-6	0.00005	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00003	0.02
				Gold metal or alloy	7440-57-5	0.00059	0.31
				Nickel	7440-02-0	0.00381	2.00
				Zinc	7440-66-6	0.00030	0.16
				Continuous Filament Fiber Glass	65997-17-3	0.01892	9.94
				Chromium(III) Oxide	1308-38-9	0.00001	0.01
				Silica amorphous	7631-86-9	0.00011	0.06
				Talc;not containing fibers like asbestos	14807-96-9	0.00059	0.31
				Cyanoguanidine	461-58-5	0.00002	0.01
				Calcium caobonate	471-34-1	0.00001	0.00
2	Solder Paste	Alloy	0.0301	Sn	7440-31-5	0.02859	95.00
				Sb	7440-36-0	0.00150	5.00
3	Passive/Active Components		0.5162	Iron Powder (Fe)	7439-89-6	0.28653	55.51
				Copper (Cu)	7440-50-8	0.17996	34.86
				Nickel (Ni)	7440-02-0	0.00684	1.33
				Tin (Sn)	7440-31-5	0.00232	0.45
				Ceramic (Ba compounds)	12047-27-7	0.04055	7.86
4	Active Ics	Silicon	0.0066	Silicon	7440-21-3	0.00655	100.00
5	Wire	Gold	0.0007	Au	7440-57-5	0.00070	99.99
6	Encapsulation	Epoxy Resin	0.6364	Fused Silica	60676-86-0	0.49126	77.20
				Epoxy Resin	non-disclosure	0.05664	8.90
				Phenol Resin	non-disclosure	0.05664	8.90
				Crytalline Silica	14808-60-7	0.01909	3.00
				Carbon Black	1333-86-4	0.00318	0.50
				Metal Hydroxide	non-disclosure	0.00955	1.50
Total Package Weight			1.3802				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts